

Amendments to the Claims:

This listing of claims replaces all prior versions and listings of claims in the application:

Listing of Claims:

1. (Currently Amended) A circuit device comprising:
a conductive pattern on which a circuit element is mounted,
wherein the conductive pattern is in a single layer and the backface of the
conductive pattern is exposed;
an insulating resin with which the circuit element and the conductive pattern are
covered;
a shielding layer ~~provided~~ on the main surface of the insulating resin;[[,]]
a through hole penetrating the insulating resin in a thickness direction,
wherein the through hole extends from the main surface of the insulating resin to
a top surface of the conductive pattern; and
a connecting means ~~formed~~ inside the through hole ~~and~~ to electrically connected
to the conductive pattern and the shielding layer.

2. (Canceled)

3. (Original) The circuit device as set forth in Claim 1, wherein the conductive
pattern electrically connected to the shielding layer is a conductive pattern serving as a ground
potential.

4. (Original) The circuit device as set forth in Claim 1, wherein the shielding layer is made from a metal.

5. (Original) The circuit device as set forth in Claim 1, wherein the shielding layer and the connecting means are made of the same material.

6. (Original) The circuit device as set forth in Claim 1, wherein the shielding layer and the connecting means are made of a plated film.

7. (Original) The circuit device as set forth in Claim 1, wherein an upper surface of the insulating resin is a rugged surface.

8. (Canceled)

9. (Withdrawn) A method for manufacturing a circuit device, the method comprising:

- preparing a conductive foil;
- forming separation grooves the depth of each of which is smaller than a thickness of the conductive foil and forming a plurality of conductive patterns;
- fixing a circuit element to the conductive pattern;
- performing a molding operation so that the circuit element is covered with an insulating resin and so that the separation grooves are filled with the insulating resin;
- forming a through-hole in the insulating resin so that the conductive pattern is exposed;
- forming a shielding layer on a surface of the insulating resin and, concurrently, forming a connecting means at a side face of and a bottom face of the through-hole;
- removing a backface of the conductive foil until the insulating resin is exposed;
- and dividing the insulating resin for each individual circuit device by dicing the insulating resin.

10. (Withdrawn) The method for manufacturing a circuit device as set forth in Claim 9, wherein the through-hole is formed by use of a laser.

11. (Withdrawn) The method for manufacturing a circuit device as set forth in Claim 9, wherein the shielding layer and the connecting means are formed according to a plating method.

12. (Withdrawn) The method for manufacturing a circuit device as set forth in Claim 9, wherein a part of the shielding layer that corresponds to a borderline between circuit devices is removed.

13. (Previously Presented) The circuit device as set forth in Claim 1, wherein the through hole has a tapered shape which narrows towards the conductive pattern.